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74ACTQ04 Quiet Series™ Hex Inverter

General Description

The ACTQ04 contains six inverters and utilizes Fairchild Quiet Series™ technology to guarantee quiet output switching and improved dynamic threshold performance. FACT Quiet Series™ features GTO™ output control and under-shoot corrector in addition to a split ground bus for superior AC MOS performance.

Features

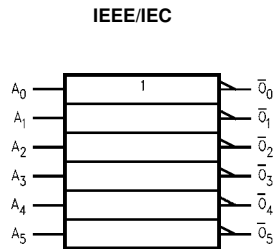
- I_{CC} reduced by 50%
- Guaranteed simultaneous switching noise level and dynamic threshold performance
- Improved latch-up immunity
- Outputs source/sink 24 mA
- Has TTL-compatible inputs

Ordering Code:

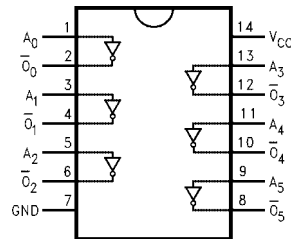
Order Number	Package Number	Package Description
74ACTQ04SC	M14A	14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150 Narrow
74ACTQ04SJ	M14D	14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74ACTQ04MTC	MTC14	14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
74ACTQ04PC	N14A	14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide

Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering code.

Logic Symbol



Connection Diagram



Pin Descriptions

Pin Names	Description
A_n	Inputs
\bar{O}_n	Outputs

FACT™, Quiet Series™, FACT Quiet Series™, and GTO™ are trademarks of Fairchild Semiconductor Corporation.

Absolute Maximum Ratings(Note 1)

Supply Voltage (V_{CC})	-0.5V to +7.0V
DC Input Diode Current (I_{IK})	
$V_I = -0.5V$	-20 mA
$V_I = V_{CC} + 0.5V$	+20 mA
DC Input Voltage (V_I)	-0.5V to $V_{CC} + 0.5V$
DC Output Diode Current (I_{OK})	
$V_O = -0.5V$	-20 mA
$V_O = V_{CC} + 0.5V$	+20 mA
DC Output Voltage (V_O)	-0.5V to $V_{CC} + 0.5V$
DC Output Source or Sink Current (I_O)	±50 mA
DC V_{CC} or Ground Current per Output Pin (I_{CC} or I_{GND})	± 50 mA
Storage Temperature (T_{STG})	-65°C to +150°C
DC Latch-up Source or Sink Current	± 300 mA
Junction Temperature (T_J)	
PDIP	140°C

Recommended Operating Conditions

Supply Voltage (V_{CC})	4.5V to 5.5V
Input Voltage (V_I)	0V to V_{CC}
Output Voltage (V_O)	0V to V_{CC}
Operating Temperature (T_A)	-40°C to +85°C
Minimum Input Edge Rate ($\Delta V/\Delta t$)	125 mV/ns
V_{IN} from 0.8V to 2.0V	
V_{CC} @ 4.5V, 5.5V	

Note 1: Absolute maximum ratings are those values beyond which damage to the device may occur. The databook specifications should be met, without exception, to ensure that the system design is reliable over its power supply, temperature, and output/input loading variables. Fairchild does not recommend operation outside of databook specifications.

DC Electrical Characteristics for ACTQ

Symbol	Parameter	V_{CC} (V)	$T_A = +25^\circ C$		Units	Conditions	
			Typ	Guaranteed Limits			
V_{IH}	Minimum HIGH Level Input Voltage	4.5	1.5	2.0	V	$V_{OUT} = 0.1V$ or $V_{CC} - 0.1V$	
		5.5	1.5	2.0			
V_{IL}	Maximum LOW Level Input Voltage	4.5	1.5	0.8	V	$V_{OUT} = 0.1V$ or $V_{CC} - 0.1V$	
		5.5	1.5	0.8			
V_{OH}	Minimum HIGH Level Output Voltage	4.5	4.49	4.4	V	$I_{OUT} = -50 \mu A$	
		5.5	5.49	5.4			
		4.5		3.86	3.76	V	$V_{IN} = V_{IL}$ or V_{IH} $I_{OH} = -24 \text{ mA}$ $I_{OH} = -24 \text{ mA}$ (Note 2)
		5.5		4.86	4.76		
V_{OL}	Maximum LOW Level Output Voltage	4.5	0.001	0.1	V	$I_{OUT} = 50 \mu A$	
		5.5	0.001	0.1			
		4.5		0.36	0.44	V	$V_{IN} = V_{IL}$ or V_{IH} $I_{OL} = 24 \text{ mA}$ $I_{OL} = 24 \text{ mA}$ (Note 2)
		5.5		0.36	0.44		
I_{IN}	Maximum Input Leakage Current	5.5		± 0.1	µA	$V_I = V_{CC}, GND$	
I_{CCT}	Maximum I_{CC} /Input	5.5	0.6		mA	$V_I = V_{CC} - 2.1V$	
I_{OLD}	Minimum Dynamic	5.5			mA	$V_{OLD} = 1.65V$ Max	
I_{OHD}	Output Current (Note 3)	5.5			mA	$V_{OHD} = 3.85V$ Min	
I_{CC}	Maximum Quiescent Supply Current	5.5		2.0	µA	$V_{IN} = V_{CC}$ or GND	
V_{OLP}	Quiet Output Maximum Dynamic V_{OL}	5.0	1.1	1.5	V	Figure 1, Figure 2 (Note 4)(Note 5)	
V_{OLV}	Quiet Output Minimum Dynamic V_{OL}	5.0	-0.6	-1.2	V	Figure 1, Figure 2 (Note 4)(Note 5)	
V_{IHD}	Minimum HIGH Level Dynamic Input Voltage	5.0	1.9	2.2	V	(Note 4)(Note 6)	
V_{ILD}	Maximum LOW Level Dynamic Input Voltage	5.0	1.2	0.8	V	(Note 4)(Note 6)	

Note 2: All outputs loaded; thresholds on input associated with output under test.

Note 3: Maximum test duration 2.0 ms, one output loaded at a time.

Note 4: DIP package.

Note 5: Max number of outputs defined as (n). Data inputs are 0V to 3V. One output @ GND.

Note 6: Max number of data inputs (n) switching. (n-1) inputs switching 0V to 3V Input-under-test switching: 3V to threshold (V_{ILD}), 0V to threshold (V_{IHD}), $f = 1 \text{ MHz}$.

AC Electrical Characteristics

Symbol	Parameter	V _{CC} (V) (Note 7)	T _A = +25°C C _L = 50 pF			T _A = -40°C to +85°C C _L = 50 pF		Units
			Min	Typ	Max	Min	Max	
t _{PLH}	Propagation Delay Data to Output	5.0	2.0	6.5	7.5	2.0	8.0	ns
t _{PHL}	Propagation Delay Data to Output	5.0	2.0	6.5	7.5	2.0	8.0	ns
t _{OSSL} t _{OSLH}	Output to Output Skew (Note 8)	5.0		0.5	1.0		1.0	ns

Note 7: Voltage Range 5.0 is 5.0V ± 0.5V.

Note 8: Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSSL}) or LOW-to-HIGH (t_{OSLH}). Parameter guaranteed by design.

Capacitance

Symbol	Parameter	Typ	Units	Conditions
C _{IN}	Input Capacitance	4.5	pF	V _{CC} = OPEN
C _{PD}	Power Dissipation Capacitance	75	pF	V _{CC} = 5.0V

FACT Noise Characteristics

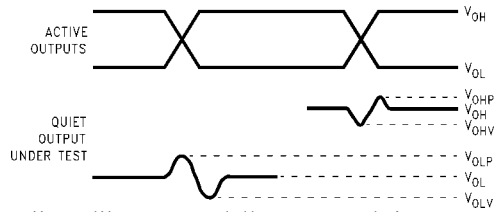
The setup of a noise characteristics measurement is critical to the accuracy and repeatability of the tests. The following is a brief description of the setup used to measure the noise characteristics of FACT™.

Equipment:

Hewlett Packard Model 8180A Word Generator
PC-163A Test Fixture
Tektronics Model 7854 Oscilloscope

Procedure:

1. Verify Test Fixture Loading: Standard Load 50 pF, 500Ω.
2. Deskew the HFS generator so that no two channels have greater than 150 ps skew between them. This requires that the oscilloscope be deskewed first. It is important to deskew the HFS generator channels before testing. This will ensure that the outputs switch simultaneously.
3. Terminate all inputs and outputs to ensure proper loading of the outputs and that the input levels are at the correct voltage.
4. Set the HFS generator to toggle all but one output at a frequency of 1 MHz. Greater frequencies will increase DUT heating and effect the results of the measurement.



Input pulses have the following characteristics: $f = 1 \text{ MHz}$, $t_r = 3 \text{ ns}$, $t_f = 3 \text{ ns}$, skew < 150 ps.

FIGURE 1. Quiet Output Noise Voltage Waveforms

5. Set the HFS generator input levels at 0V LOW and 3V HIGH for ACT devices and 0V LOW and 5V HIGH for AC devices. Verify levels with an oscilloscope.

V_{OLP}/V_{OLV} and V_{OHP}/V_{OHV} :

- Determine the quiet output pin that demonstrates the greatest noise levels. The worst case pin will usually be the furthest from the ground pin. Monitor the output voltages using a 50Ω coaxial cable plugged into a standard SMB type connector on the test fixture. Do not use an active FET probe.
- Measure V_{OLP} and V_{OLV} on the quiet output during the worst case transition for active and enable. Measure V_{OHP} and V_{OHV} on the quiet output during the worst case transition for active and enable.
- Verify that the GND reference recorded on the oscilloscope has not drifted to ensure the accuracy and repeatability of the measurements.

V_{ILD} and V_{IHD} :

- Monitor one of the switching outputs using a 50Ω coaxial cable plugged into a standard SMB type connector on the test fixture. Do not use an active FET probe.
- First increase the input LOW voltage level, V_{IL} , until the output begins to oscillate or steps out a min of 2 ns. Oscillation is defined as noise on the output LOW level that exceeds V_{IL} limits, or on output HIGH levels that exceed V_{IH} limits. The input LOW voltage level at which oscillation occurs is defined as V_{ILD} .
- Next decrease the input HIGH voltage level, V_{IH} , until the output begins to oscillate or steps out a min of 2 ns. Oscillation is defined as noise on the output LOW level that exceeds V_{IL} limits, or on output HIGH levels that exceed V_{IH} limits. The input HIGH voltage level at which oscillation occurs is defined as V_{IHD} .
- Verify that the GND reference recorded on the oscilloscope has not drifted to ensure the accuracy and repeatability of the measurements.

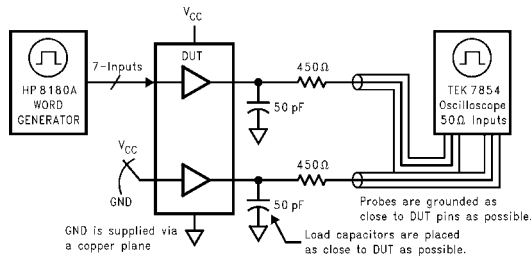
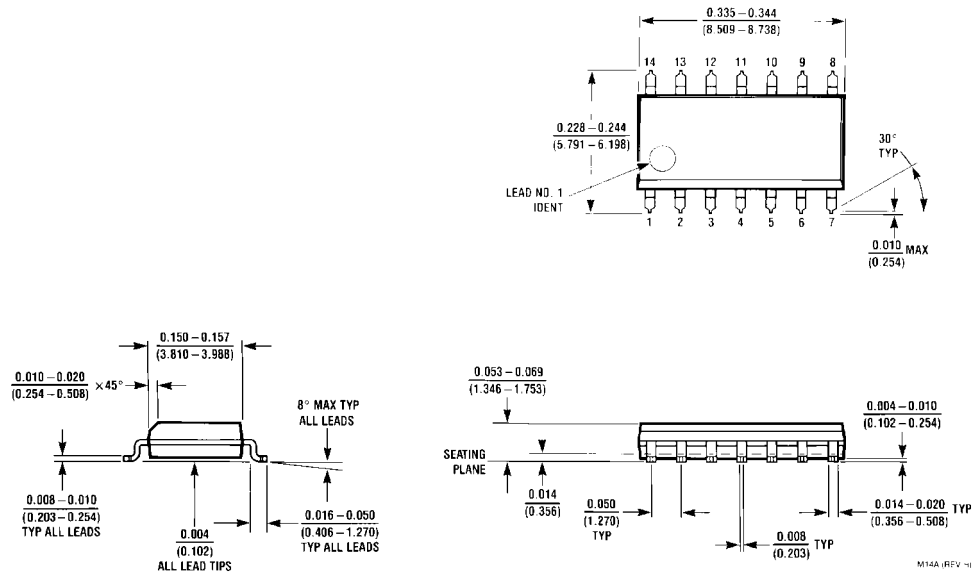


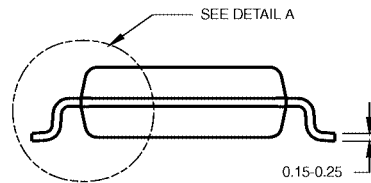
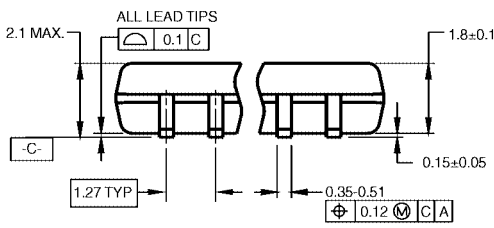
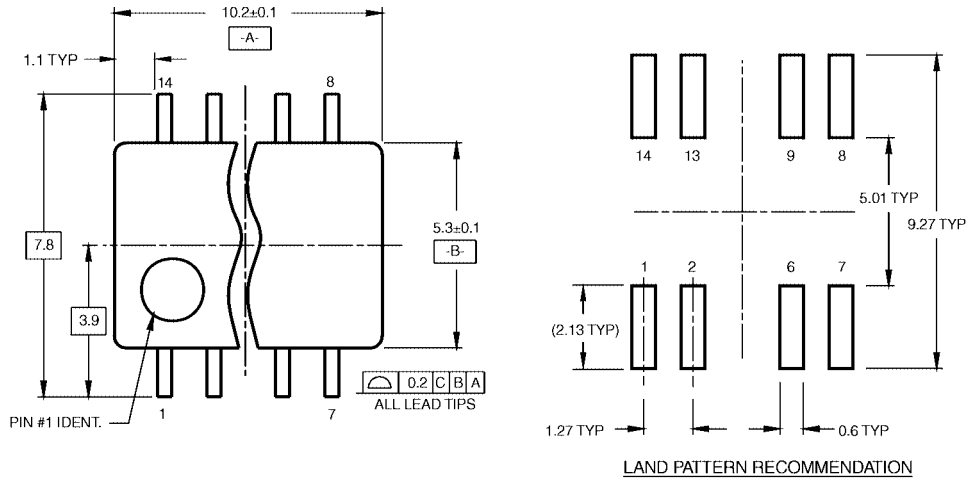
FIGURE 2. Simultaneous Switching Test Circuit

Physical Dimensions inches (millimeters) unless otherwise noted



**14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150 Narrow
Package Number M14A**

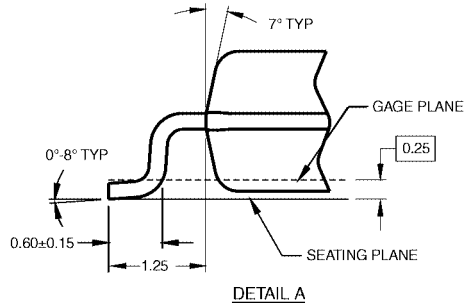
Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



DIMENSIONS ARE IN MILLIMETERS

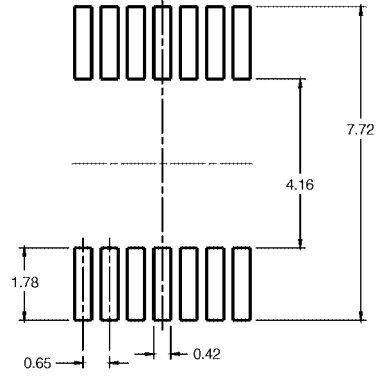
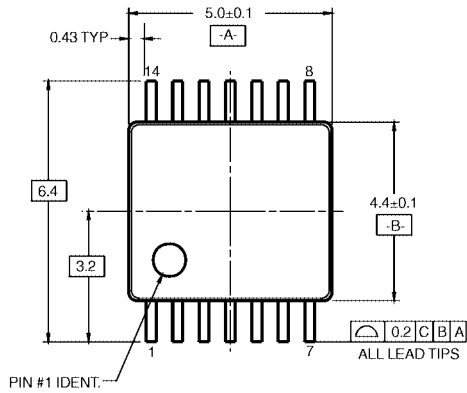
- NOTES:
 A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.
 B. DIMENSIONS ARE IN MILLIMETERS.
 C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

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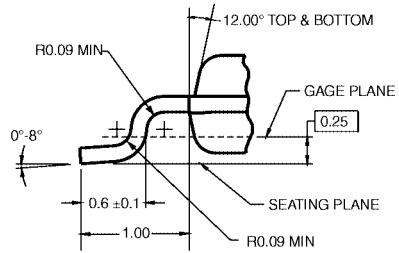
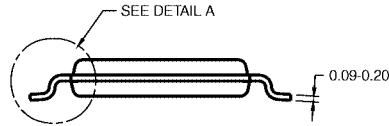
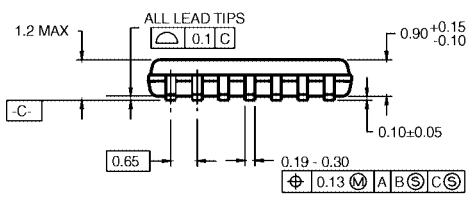


**14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
 Package Number M14D**

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



LAND PATTERN RECOMMENDATION



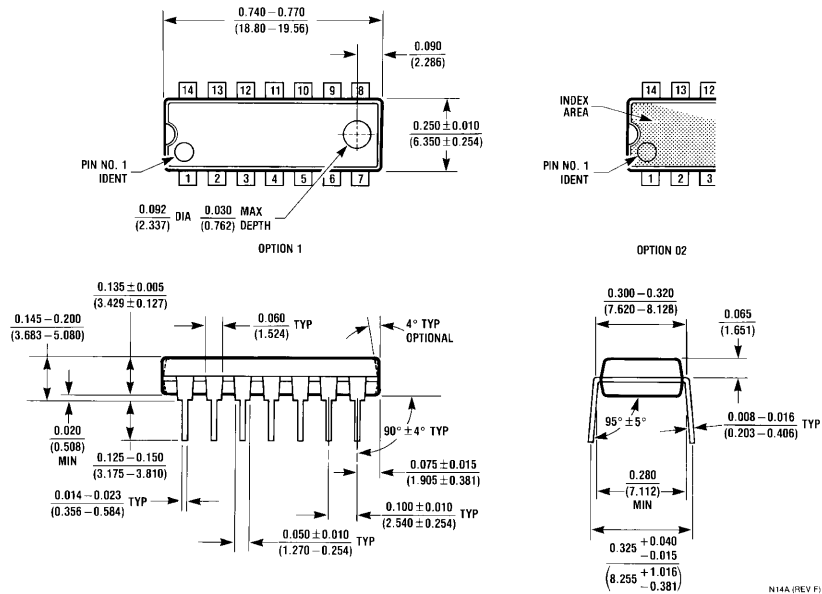
DETAIL A

- NOTES:
- A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AB, REF NOTE 6, DATE 7/93.
 - B. DIMENSIONS ARE IN MILLIMETERS.
 - C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
 - D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

MTC14RevC3

**14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
Package Number MTC14**

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



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